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## WHAT IS CLAIMED IS:

1. A semiconductor device comprising:

a substrate having a main surface including a first area, a second area surrounding the first area, and a third area surrounding the second area;

a first insulating protective film that is provided in the first area and formed in a shape having no angles;

a second insulating protective film provided in the third area;

a semiconductor chip that is provided on the first insulating protective film and has a bottom surface facing to the first insulating protective film; and

a sealing resin covering the semiconductor chip, wherein the bottom surface of the semiconductor chip covers the first area.

2. A semiconductor device comprising:

a semiconductor chip having a bottom surface including a plurality of angular portions;

a substrate having a main surface including a first area, a second area surrounding the first area, and a third area surrounding the second area;

a first insulating protective film having an outer edge which is provided in the first area, wherein the first insulating protective film faces to the bottom surface of the semiconductor chip, wherein the first insulating

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protective film has no angles on the outer edge closest to an angular portion of the bottom surface;

a second insulating protective film provided in the third area; and

5 a sealing resin covering the semiconductor chip;  
wherein the bottom surface of the semiconductor chip covers the first area.

3. A semiconductor device comprising:

10 a substrate having a main surface including a first area, a second area surrounding the first area, a third area surrounding the second area, and a fourth area surrounding the third area;

an insulating protective film which is provided  
15 only in the first and fourth areas;

an adhesive layer which is provided in the second area;

a semiconductor chip which is provided on the insulating protective film in the first area and on the  
20 adhesive layer; and

a sealing resin covering the semiconductor chip.

4. The semiconductor device according to Claim 3,  
wherein no interconnections are provided on the main  
25 surface of the substrate under an outer edge of the semiconductor chip.

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5. A semiconductor device comprising:

a substrate having a main surface, wherein an interconnection is provided on the main surface;

an insulating protective film which is provided on the main surface;

a semiconductor chip which is provided on the insulating protective film; and

a sealing resin which covers the semiconductor chip,

wherein a thickness of the interconnection provided under an outer edge of the semiconductor chip is grater than a thickness of the interconnection provided in the other portion.

6. The semiconductor device according to Claim 5, wherein a width of the interconnection provided under the outer edge of the semiconductor chip is grater than a width of the interconnection provided in the other portion.